1 Form A APSEMI DIP-4 SMD-4 Load Voltage:60V Load Current:3.0A

TSCA Parameter Symbol Units Rating E534710 Load Voltage VL V 60 Load Current А ΙL 3 0.055 On-Resistance Ron Ω I/O Breakdown Voltage 5000 Vrms V/ıo (+) Input 1 \cap $\sqrt{2}$ E1 IF (AC.DC) SMD-4 1 I FD Anode DIP-4 AC/DC 2. LED Cathode

APSEMI PhotoRelays

R

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

3.4. Drain(MOS FET)

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
 - Small package size

Function

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con | guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

Robotics

Aerospace

Process Control

Energy Management

Home/Safety security systems

Reed Relay EMR Replacement

Programmable Controllers

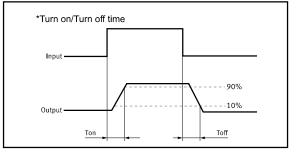
Applications

These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching •
- Multiplexers
- Meter reading systems .
- Data acquisition
- Medical equipment .
- Battery monitoring
- I/O Sub-Systems

TPYES

| Category | Output rating | | | | Packing quantity | |
|----------|---------------|-----------------------------------|----------|------------|------------------|------------|
| | Load voltage | Load voltage Load current Package | | Part No. | | |
| AC/DC | 60V | 60V 3.0A DIP4 SMD4 | COV 0.04 | DIP4 | APY252G3E | 50pcs/tube |
| | | | SMD4 | APY252G3EH | 1000pcs/1reel | |





APY252G3E_EH



Absolute Maximum Ratings (Ta = 25°C)

| Item | | Symbol | Value | Units | Note | |
|---------------------------|--------------------------|------------------|-------------|------------------|---------------------|--|
| Continuous LED Current | | lF | 50 | mA | | |
| Input | Peak LED Current | IFP | 1000 | mA | f=100Hz, duty=1% | |
| | LED Reverse Voltage | VR | 5 | V | | |
| | Input Power Dissipation | Pln | 75 | mW | | |
| Output | Load Voltage | VL | 60 | V(AC peak or DC) | | |
| | Load Current | l. | 3.0 | А | | |
| | Peak Load Current | Peak | 6.0 | А | 100ms(1 pulse) | |
| | Output Power Dissipation | Pout | 500 | mW | | |
| Total Power Dissipation | | Ρτ | 650 | mW | | |
| I/O Breakdown Voltage | | Vı/o | 5000 | Vrms | RH=60%, 1min | |
| Operating Temperature | | Topr | -40 to +85 | °C | | |
| Storage Temperature | | Tstg | -40 to +100 | °C | | |
| Pin Soldering Temperature | | T _{sol} | 260 | °C | 10 sec max. | |

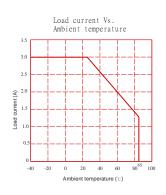
Electrical Specifications (Ambient Temperature: 25°C)

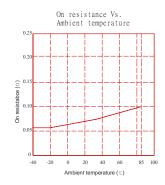
| Item | | Symbol | MIN. | TYP. | MAX. | Units | Conditions | |
|---------------------|------------------------------|--------|------|-------|-------|-------|---|--|
| LED Forward Voltage | | VF | 1.2 | 1.32 | 1.6 | V | I⊧=10mA | |
| Input | Operation LED Current | F on | | 1.0 | 5.0 | mA | | |
| | Recovery LED Current | IF off | | 0.35 | 0.5 | mA | | |
| | Recovery LED Voltage | VF off | 0.7 | | | V | | |
| Output | On-Resistance | Ron | | 0.055 | 0.085 | Ω | I⊧=5mA,I∟=100mA, Time to flow is within 1 sec. | |
| | Off-State Leakage Current | ILeak | 0.01 | 0.03 | 0.10 | uA | V₋=Rating | |
| | Output Capacitance | Cout | | 185 | | pF | V∟=0, f=1MHz | |
| Transmis sion | Turn-On Time | Ton | 0.2 | 1.0 | 2.0 | ms | l⊧=5mA, l∟=100mA, | |
| | Turn-Off Time | Toff | 0.04 | 0.05 | 0.1 | ms | | |
| Coupled | I/O Isolation Resistance | Rı/o | 5 | | | GΩ | DC500V | |
| | I/O Capacitance | Cı/o | | 0.8 | 1.5 | pF | f=1MHz | |

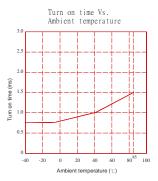
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

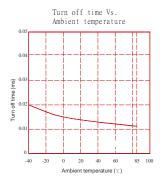
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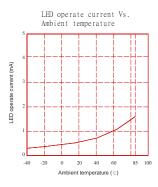
Engineering Data

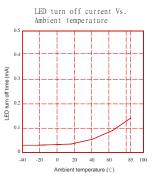




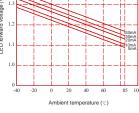


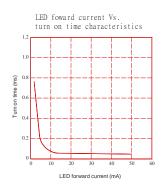




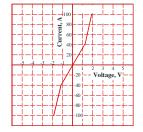


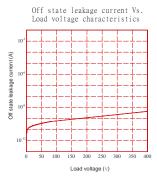
LED forward voltage Vs. Ambient temperature 13 L LED forward voltage (V) 1 i



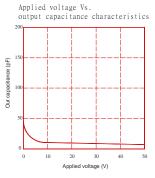


Voltage Vs. currennt characteristics of output at MOS portion





LED foward current Vs. turn off time characteristics 0.1 ns) , e 0.0+ # 0 Turn LED forward current (mA)



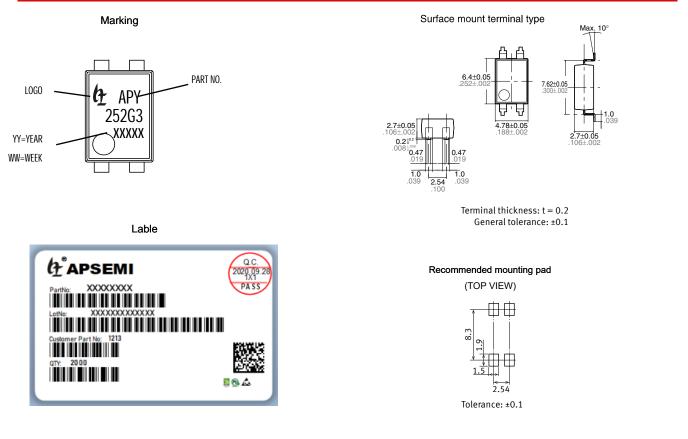
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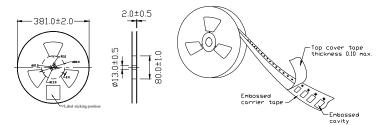
Dimensions and SMD-4 Package Unit: mm

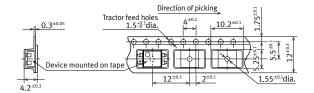
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Tape dimensions (tape reel)



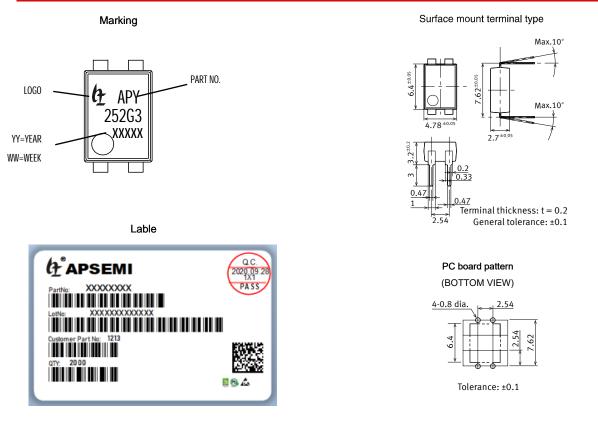


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Dimensions and DIP-4 Package Unit: mm



Tape dimensions (tape reel)

DIP type

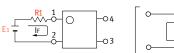
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

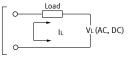




Using Methods

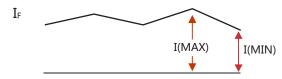
Examples of resistance value to control LED forward current (IF=5mA)





| E1 | R1 (Approx) |
|------|-------------|
| 3.3V | 300 Ω |
| 5.0V | 600 Ω |
| 12V | 1.9KΩ |
| 24V | 4.1K Ω |

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



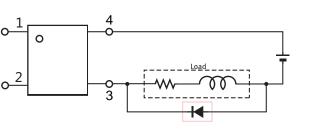
Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

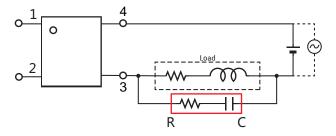
| Characteristic | Symbol | Min | Тур. | Max | Unit |
|-----------------|----------------|-----|------|-----|------|
| Forward current | ١ _F | 5.0 | 7.0 | 30 | mA |

Protection Circuit

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.



CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.



When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.

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